TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ($L^2-\pi$ -MOSV)

2SK2311

Chopper Regulator, DC-DC Converter and Switching Regulator Applications

• 4 V gate drive

• Low drain–source ON resistance $: R_{DS}(ON) = 36 \text{ m}\Omega \text{ (typ.)}$ • High forward transfer admittance $: |Y_{fs}| = 16 \text{ S (typ.)}$ • Low leakage current $: I_{DSS} = 100 \text{ }\mu\text{A (max)} \text{ (V}_{DS} = 60 \text{ V)}$

• Enhancement-mode : $V_{th} = 0.8 \sim 2.0 \text{ V (VDS} = 10 \text{ V, ID} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	60	٧
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	60	V
Gate-source voltage		V_{GSS}	±20	V
Drain current	DC (Note 1)	I _D	25	Α
	Pulse (Note 1)	I_{DP}	100	Α
Drain power dissipation (Tc = 25°C)		P_{D}	40	W
Single pulse avalanche energy (Note 2)		E _{AS}	156	mJ
Avalanche current		I _{AR}	25	Α
Repetitive avalanche energy (Note 3)		E _{AR}	3.5	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature range		T _{stg}	-55~150	°C

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	3.125	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C .

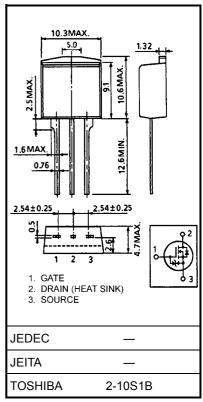
Note 2: V_{DD} = 25 V, T_{ch} = 25°C (initial), L = 339 $\mu H,\,R_{G}$ = 25 $\Omega,\,I_{AR}$ = 25 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

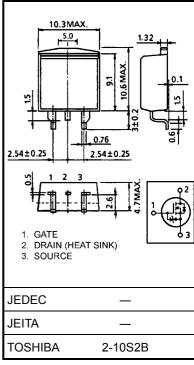
This transistor is an electrostatic sensitive device.

Please handle with caution.

Unit: mm



Weight: 1.5 g (typ.)



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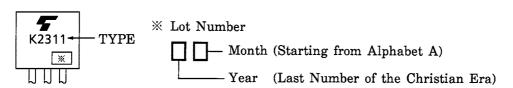
Electrical Characteristics (Ta = 25°C)

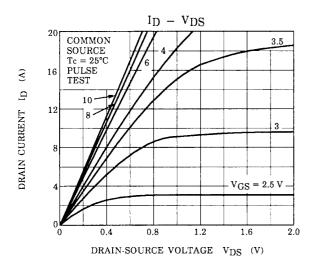
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V	1	_	100	μA
Drain-source br	eakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	60	_	_	V
Gate threshold v	oltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 4 V, I _D = 12 A	-	57	80	m0
			V _{GS} = 10 V, I _D = 12 A	_	36	46	mΩ
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 12 A	10	16	_	S
Input capacitano	e	C _{iss}			1000	_	
Reverse transfer	r capacitance	C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	200	_	pF
Output capacitance		Coss			550	_	
Switching time	Rise time	t _r	$V_{GS} \stackrel{10 \text{ V}}{\circ} V_{OUT}$ $R_{L} = 2.5 \Omega$ $V_{DD} = 30 \text{ V}$	_	20	_	- ns
	Turn-on time	t _{on}		l	30		
	Fall time	t _f		_	55	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\mathbf{W}} = 10 \ \mu s$	_	130	_	
Total gate charge (Gate-source plus gate-drain)		Qg	V _{DD} ≈ 48 V, V _{GS} = 10 V, I _D = 25 A		38		
Gate-source charge		Q _{gs}			25	_	nC
Gate-drain ("miller") charge		Q_{gd}		_	13		

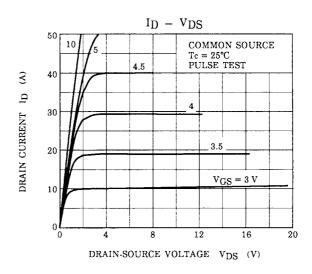
Source-Drain Ratings and Characteristics (Ta = 25°C)

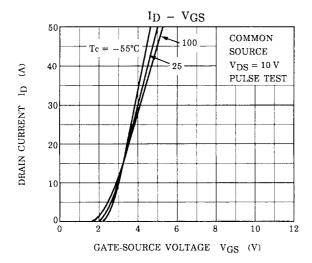
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_		_	25	Α
Pulse drain reverse current (Note 1)	I _{DRP}	-		_	100	Α
Forward voltage (diode)	V_{DSF}	I _{DR} = 25 A, V _{GS} = 0 V	_	_	-1.8	V
Reverse recovery time	t _{rr}	I _{DR} = 25 A, V _{GS} = 0 V	_	50	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 50 A / μs		35	_	μC

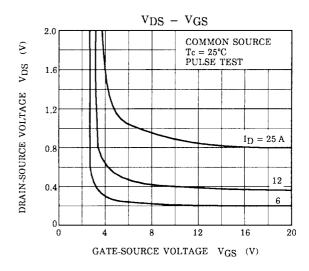
Marking

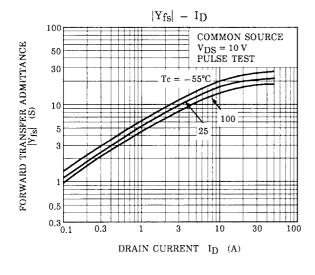


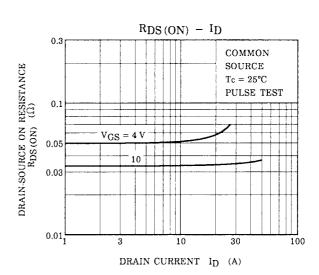




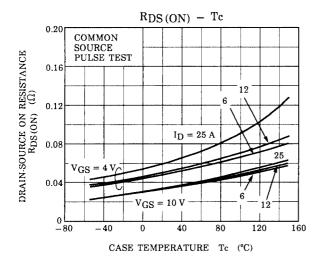


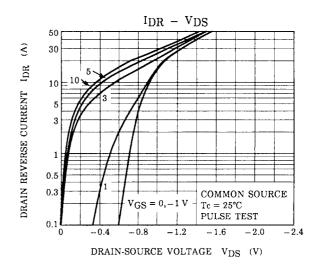


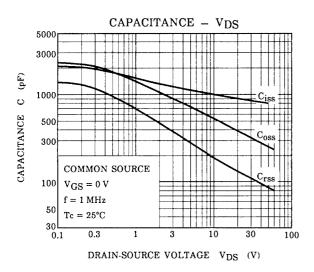


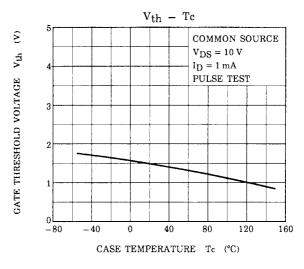


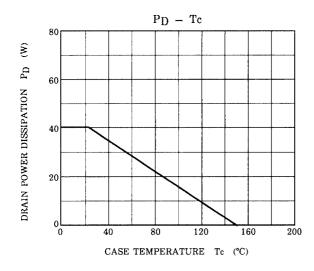
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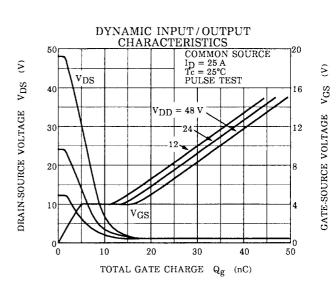




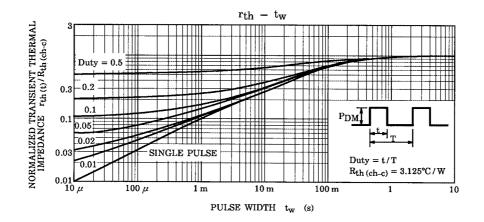


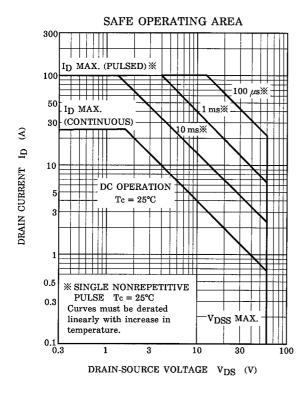


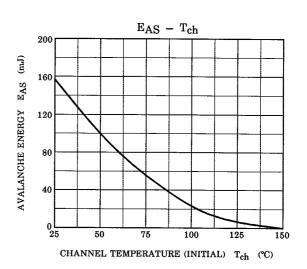


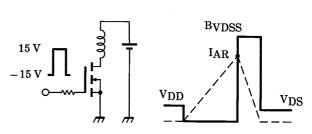


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TEST CIRCUIT

WAVE FORM

$$R_{G} = 25 \Omega$$

 $V_{DD} = 25 V, L = 339 \mu H$

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

5

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